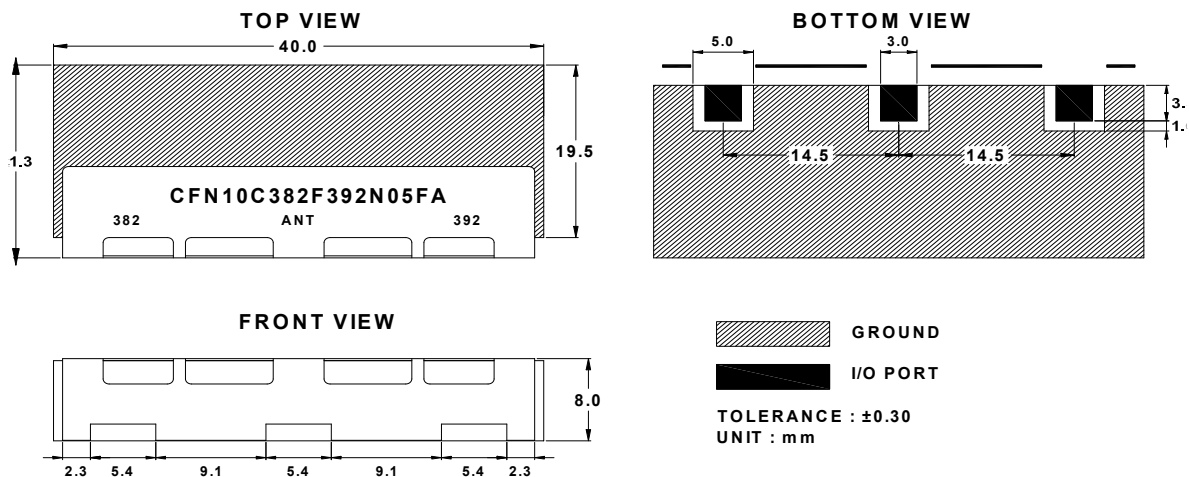


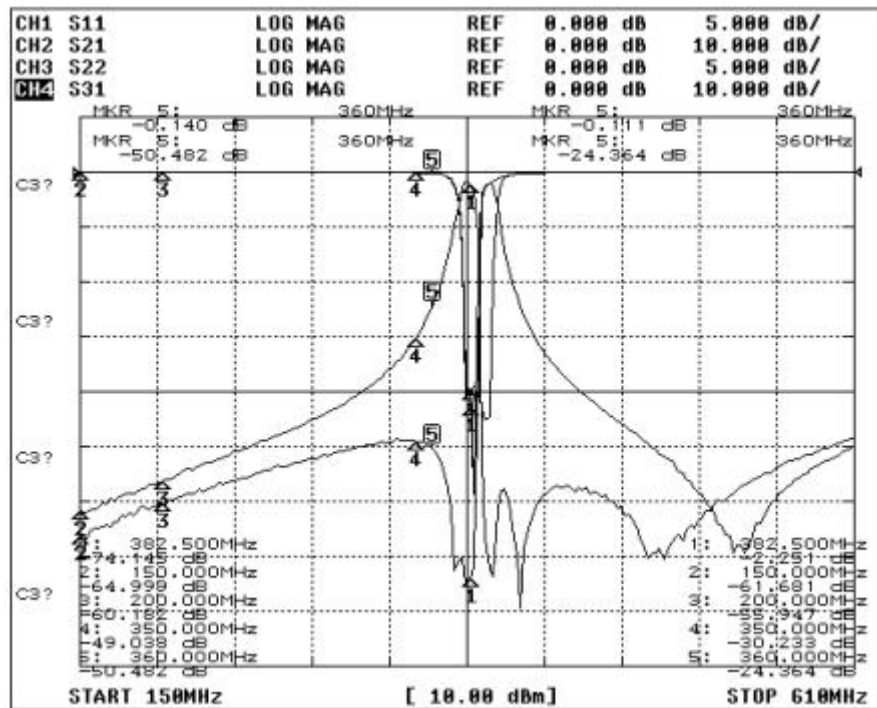
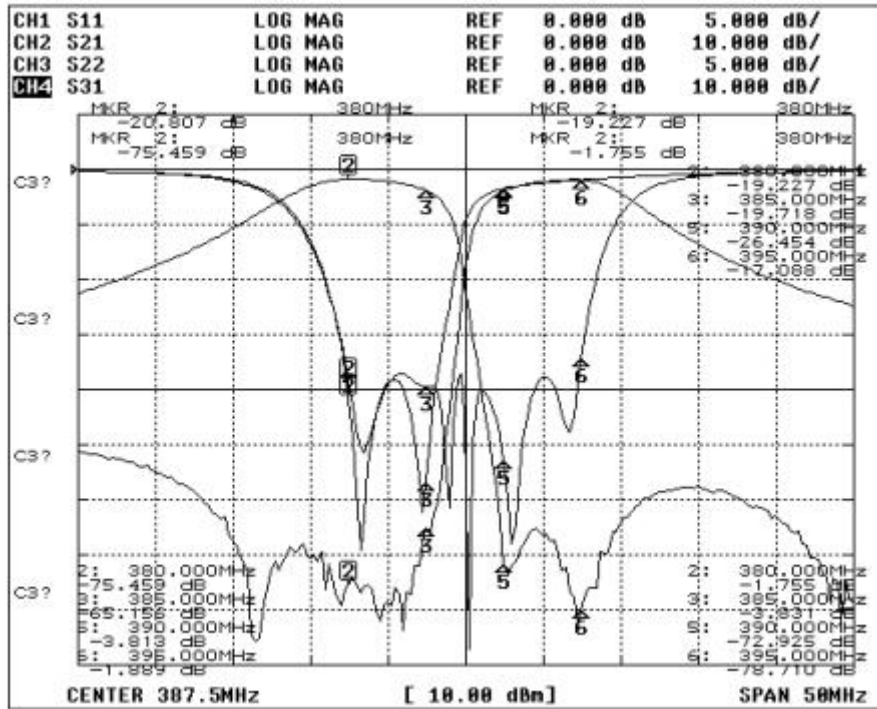
**Electrical Specification**

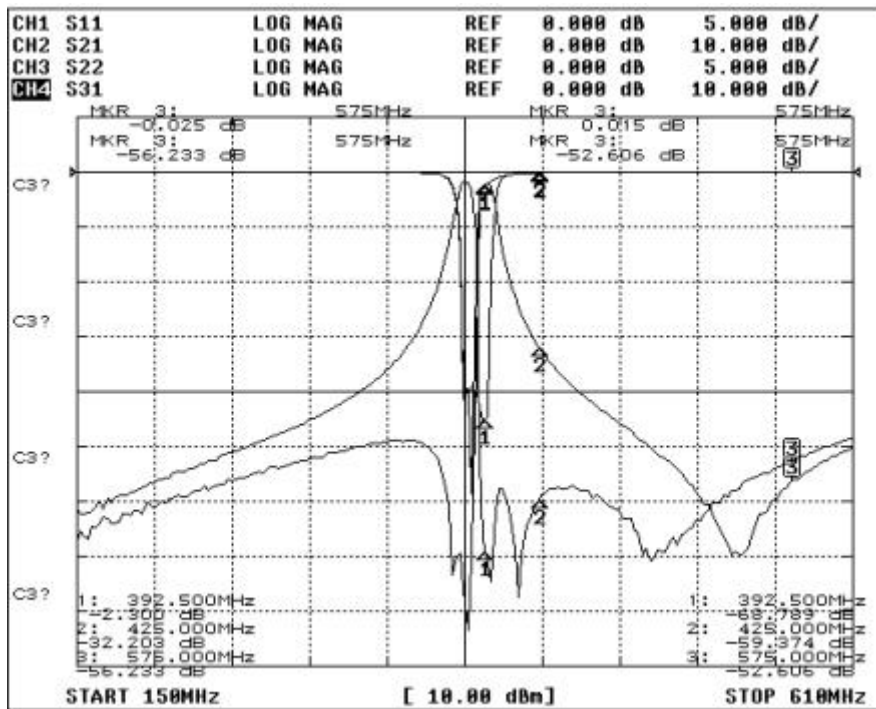
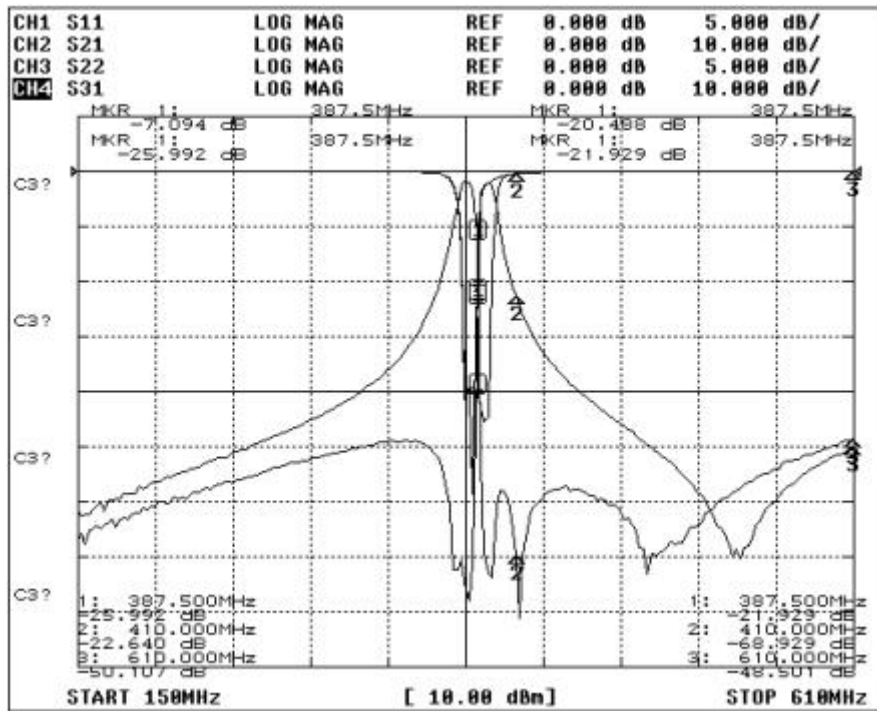
ITEMS	ANT >> Low	ANT >> High	UNIT
Center Frequency [fo]	382.5	392.5	MHz
Bandwidth [BW]	fo ±2.5 [380.0 ~ 385.0]	fo ±2.5 [390.0 ~ 395.0]	MHz
Insertion Loss in BW	4.0	4.0	dB max
Ripple in BW	2.5	2.5	dB max
Return Loss in BW	15.0	15.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	50.0 dB min. @ [150.0 ~ 200.0]	57.0 dB min. @ [150.0 ~ 200.0]	MHz
	30.0 dB min. @ [200.0 ~ 350.0]	47.0 dB min. @ [200.0 ~ 360.0]	MHz
	25.0 dB min. @ [350.0 ~ 360.0]	60.0 dB min. @ [380.0 ~ 385.0]	MHz
	18.0 dB min. @ [387.5 ~ 390.0]	18.0 dB min. @ [385.0 ~ 387.5]	MHz
	60.0 dB min. @ [390.0 ~ 395.0]	20.0 dB min. @ [410.0 ~ 425.0]	MHz
	45.0 dB min. @ [410.0 ~ 610.0]	30.0 dB min. @ [425.0 ~ 575.0]	MHz
	dB min. @ [200.0 ~ 360.0]	45.0 dB min. @ [575.0 ~ 610.0]	MHz
Group Delay Variation			ns max
Input Power	3.0		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40°C to +85°C		

**Mechanical Specification**

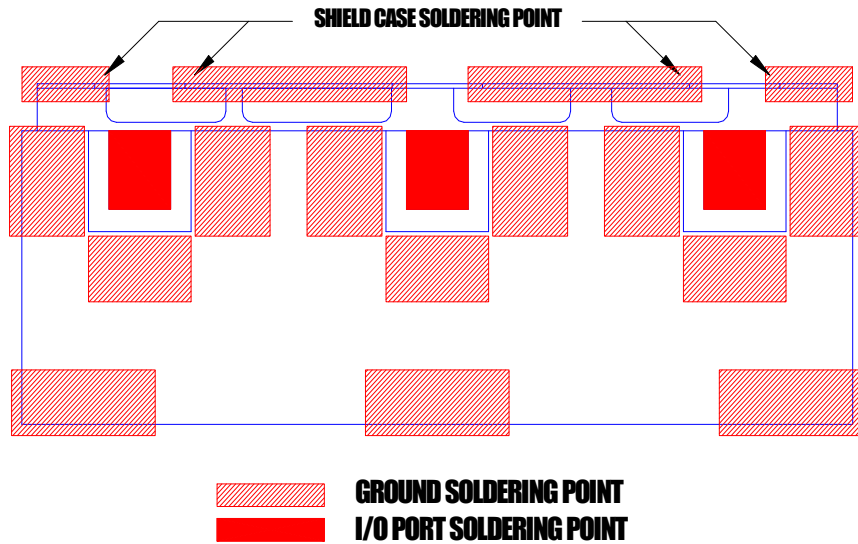


Plot Data

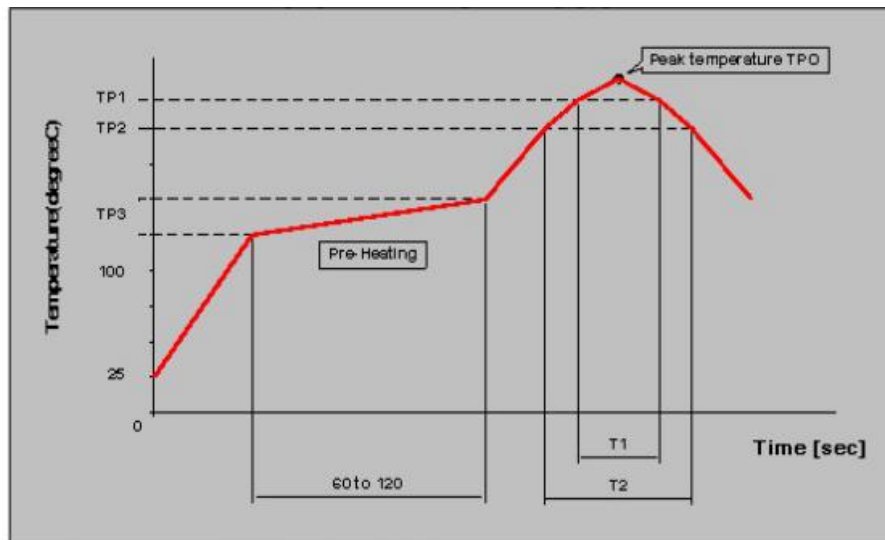




Recommended PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245 $\pm$ 5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260 $\pm$ 5/0	240	20	220	70	150 to 180